

LNJ314G83RA

Hight Bright Surface Mounting Chip LED

USS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	40	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	50	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color

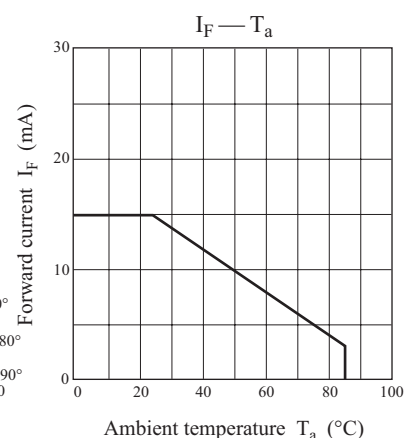
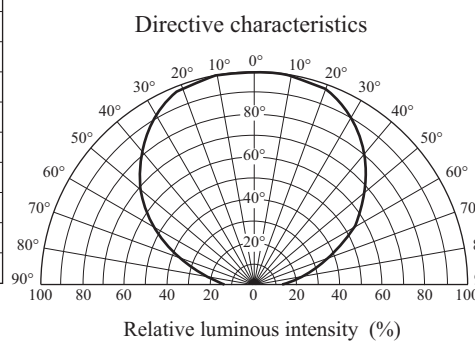
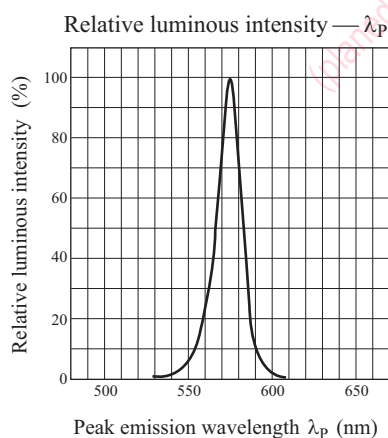
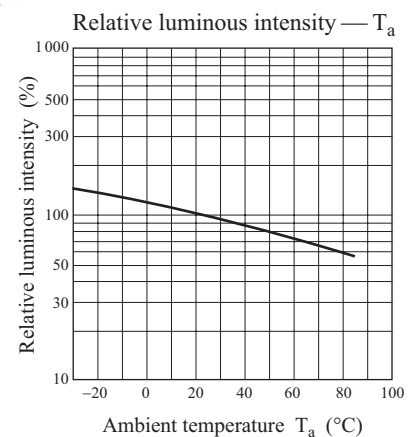
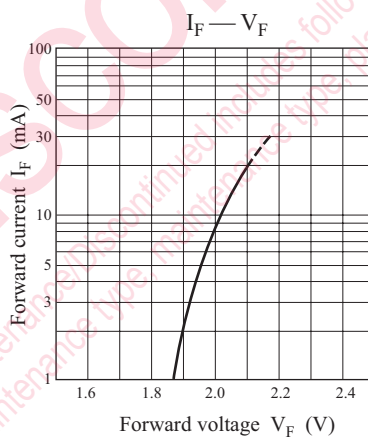
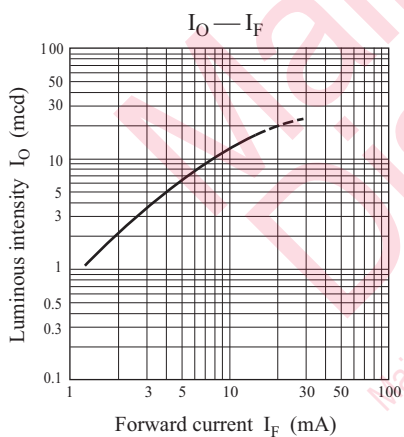
- Yellow Green

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

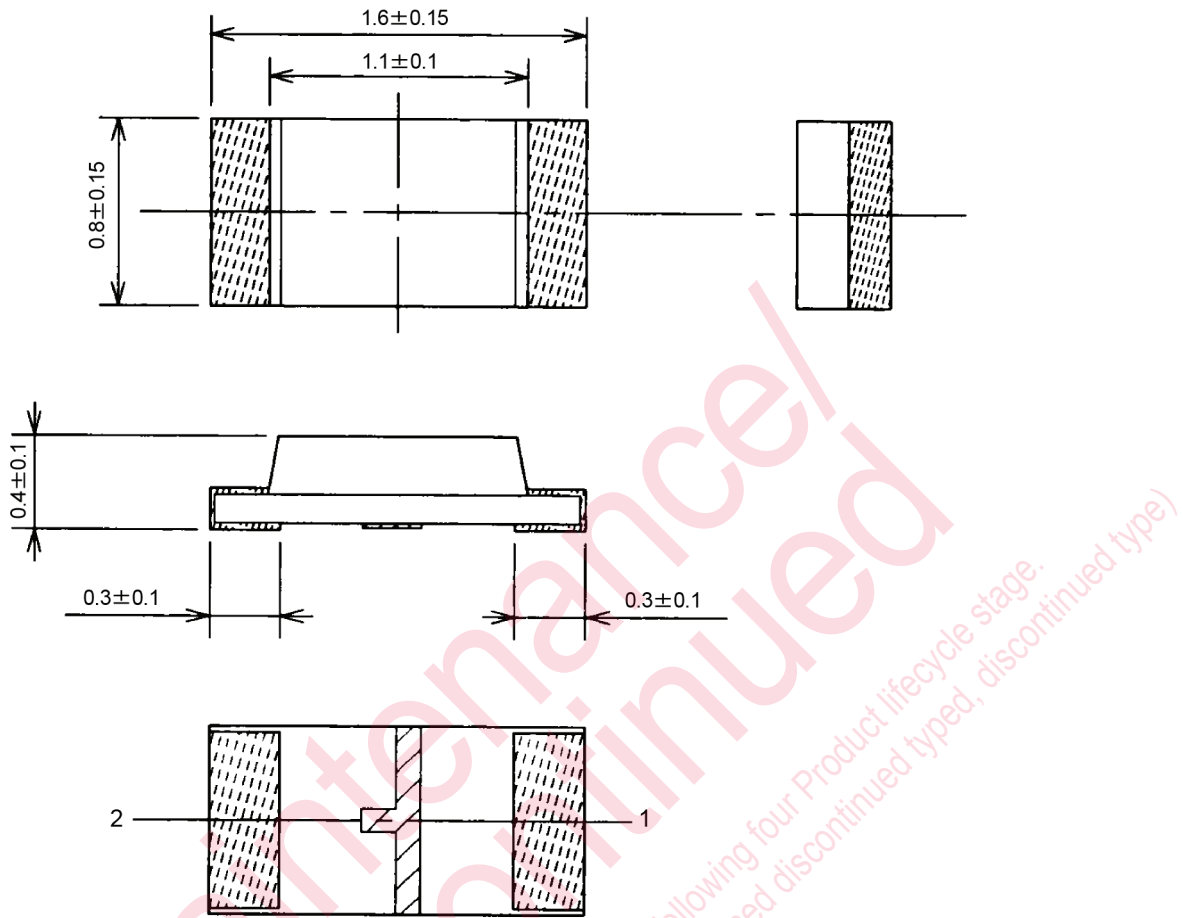
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 10 \text{ mA}$	6.4	12		mcd
Reverse current	I_R	$V_R = 4 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10 \text{ mA}$		2.03	2.50	V
Peak emission wavelength	λ_p	$I_F = 10 \text{ mA}$		575		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		15		nm

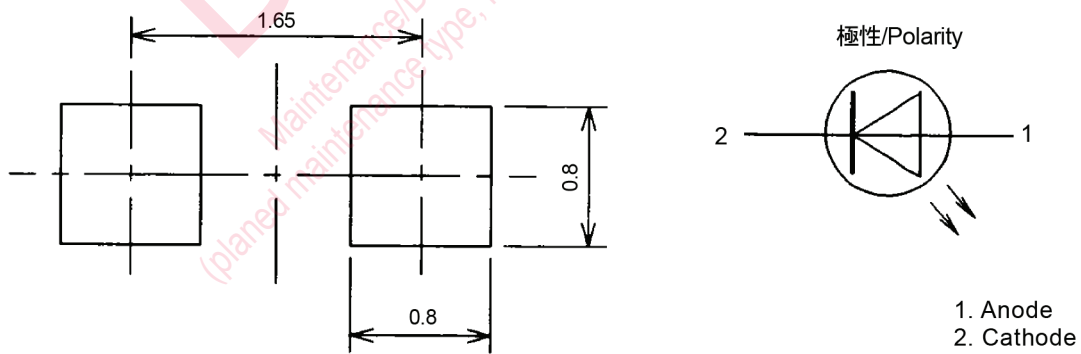
Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)



〈推奨パターン/Recommended land layout〉



(注 1) パッケージ寸法については電極バリを含まない。
 (Note1) Electrode projection is not included in the package dimensions.

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